



SOT82

plastic single-ended package; 3 leads (in-line)

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	SIP3
Package type industry code	SIP3
Package style descriptive code	SIP (single in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	SIP3; TO-220
Mounting method type	T (through-hole mount)
Issue date	11-6-1997

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		10.5	-	10.8	11.1	mm
E	package width		7.2	-	7.5	7.8	mm
A ₂	package height		2.3	-	2.6	2.8	mm
n ₂	actual quantity of termination		-	-	3	-	



2. Package outline

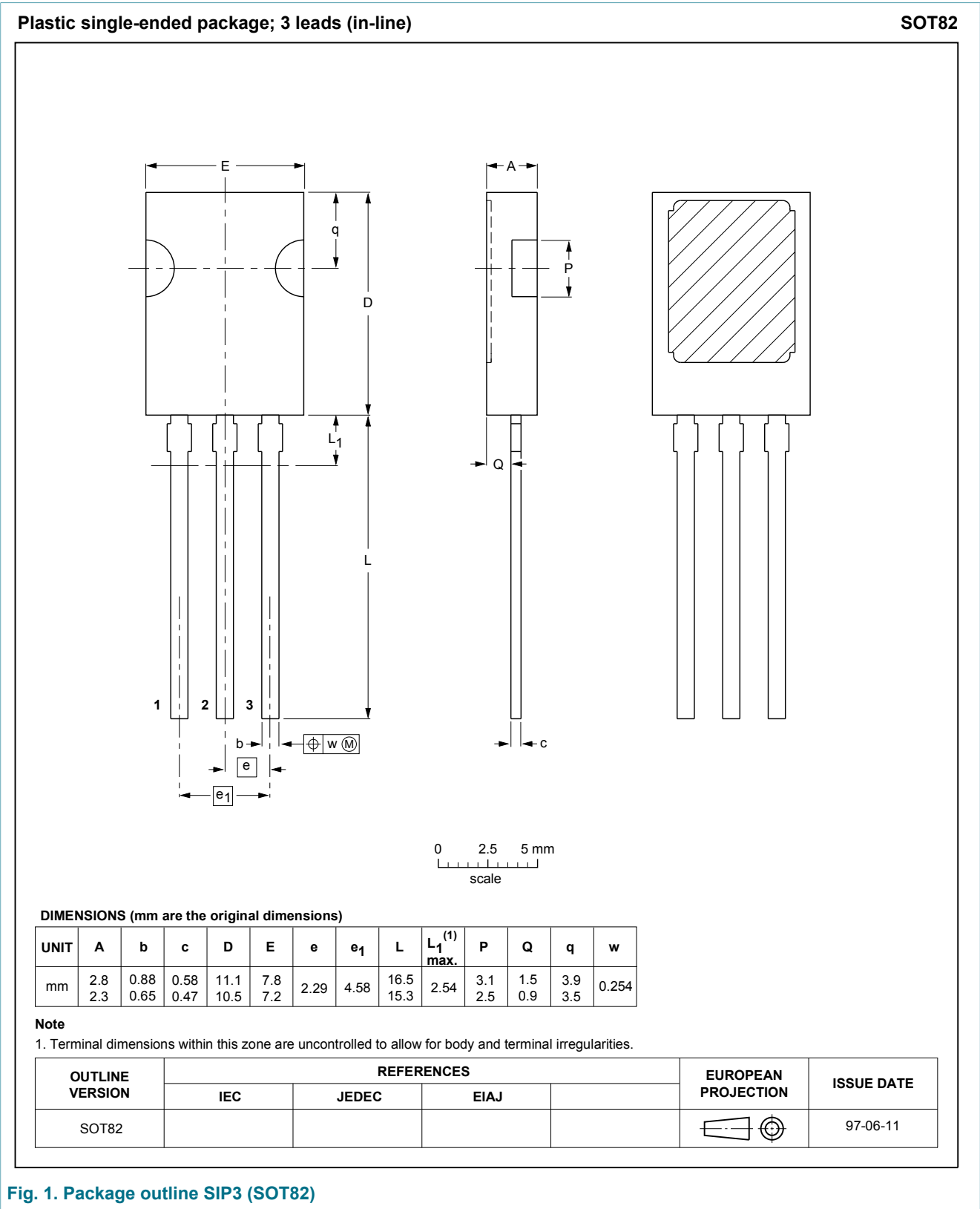


Fig. 1. Package outline SIP3 (SOT82)

3. Legal information

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4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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